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ABSTRACT OF THE DISCLOSURE

RESIN COATED MEMBER FOR USE IN SEMICONDUCTOR DEVICE TREATMENT AND METHOD FOR MANUFACTURING THE SAME

There is provided a resin coated member for use in semiconductor device treatment having a superior resistance to plasma etching which causes no abnormal etching, and neither scores the semiconductor device nor causes contamination of the semiconductor device due to peeling off of the resin coating and development of particles even at the time of cleaning treatment, and to provide a method for manufacturing the same, an entire surface of the member being coated with a fluorine-contained resin or an engineering plastic in such a manner as to prevent pinholing, and the coating being preferably 50 μm thick or more and surface roughness Ra of the same being 1 μm or less.